



### **60V P-CHANNEL ENHANCEMENT MODE MOSFET**

## **Product Summary**

BV <sub>DSS</sub>	R <sub>DS(ON)</sub> max	I <sub>D</sub> max T <sub>A</sub> = +25°C		
-60V	110mΩ @ V <sub>GS</sub> = -10V	-4.5A		
	130mΩ @ V <sub>GS</sub> = -4.5V	-4.2A		

## **Description and Applications**

This MOSFET has been designed to minimize the on-state resistance  $(R_{DS(ON)})$  and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- Backlighting
- Power Management Functions
- DC-DC Converters

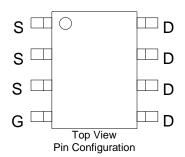
## **Features and Benefits**

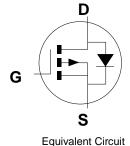
- Low On-Resistance
- Low Gate Threshold Voltage
- Low Input Capacitance
- · Fast Switching Speed
- Low Input/ Output Leakage
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP Capable (Note 4)

### **Mechanical Data**

- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound.
   UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals Connections: See Diagram
- Terminals: Finish Matte Tin Annealed over Copper Lead Frame. Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.072g (Approximate)







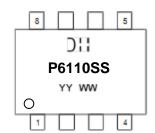
### Ordering Information (Note 5)

Part Number	Case	Packaging
DMP6110SSSQ-13	SO-8	2500/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. Automotive products are AEC-Q101 qualified and are PPAP capable. Refer to http://www.diodes.com/product\_compliance\_definitions.html.
- 5. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

# **Marking Information**



);; = Manufacturer's Marking
P6110SS = Product Type Marking Code
YYWW = Date Code Marking
YY = Year Code (ex: 14 = 2014)
WW = Week Code (01 to 53)



# Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	;		Symbol	Value	Unit	
Drain-Source Voltage			V <sub>DSS</sub>	-60	V	
Gate-Source Voltage			V <sub>GSS</sub>	±20	V	
Drain Current (Note 7) V <sub>GS</sub> = -10V	t < 10s	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I <sub>D</sub>	-4.5 -3.6	А	
Maximum Body Diode Forward Current (Not		I <sub>S</sub>	-2.1	A		
Pulsed Drain Current (10μs Pulse, Duty Cycle = 1%)			I <sub>DM</sub>	-19	А	
Avalanche Current (Note 8) L = 0.1mH		I <sub>AS</sub>	-17.6	A		
Avalanche Energy (Note 8) L = 0.1mH			E <sub>AS</sub>	15.4	mJ	

# Thermal Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 6)		P <sub>D</sub>	1.5	W
The recoil Begintenes, It maties to Applicat (Nets C)			80	°C/W
Thermal Resistance, Junction to Ambient (Note 6)	t<10s	$R_{ heta JA}$	48	°C/W
Total Power Dissipation (Note 7)		P <sub>D</sub>	2.0	W
Thermal Resistance, Junction to Ambient (Note 7)	Steady State	D	61	°C/W
Thermal Resistance, Junction to Ambient (Note 1)	t<10s	$R_{\theta JA}$	37	°C/W
Thermal Resistance, Junction to Case		$R_{ heta JC}$	6.4	°C/W
Operating and Storage Temperature Range		$T_{J,}T_{STG}$	-55 to +150	°C

# **Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 9)							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	-60	_	_	V	$V_{GS} = 0V, I_D = -250\mu A$	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	_	_	-1	μΑ	V <sub>DS</sub> = -48V, V <sub>GS</sub> = 0V	
Gate-Source Leakage	I <sub>GSS</sub>	_	_	100	nA	$V_{GS} = \pm 16V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 9)							
Gate Threshold Voltage	V <sub>GS(TH)</sub>	-1	_	-3	V	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	
Static Drain-Source On-Resistance		_	86	110	mΩ	$V_{GS} = -10V, I_D = -4.5A$	
Static Diam-Source On-Resistance	R <sub>DS(ON)</sub>	_	98	130	11177	V <sub>GS</sub> = -4.5V, I <sub>D</sub> =-3.5A	
Diode Forward Voltage	$V_{SD}$	_	-0.7	-1.2	V	V <sub>GS</sub> = 0V, I <sub>S</sub> = -1A	
DYNAMIC CHARACTERISTICS (Note 10)					·		
Input Capacitance	C <sub>iss</sub>	_	1030				
Output Capacitance	Coss		49.1	_	pF	$V_{DS} = -30V$ , $V_{GS} = 0V$ , $f = 1.0MHz$	
Reverse Transfer Capacitance	C <sub>rss</sub>	Γ <u></u>	38.7		<u></u>		
Gate Resistance	$R_{G}$	_	13.6	_	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$	
Total Gate Charge (V <sub>GS</sub> = -4.5V)	Qg	_	9.5	_			
Total Gate Charge (V <sub>GS</sub> = -10V)	Qg	_	19.4	_	nC	V 20V I 5A	
Gate-Source Charge	Q <sub>gs</sub>	_	2.3	_	nc	$V_{DS} = -30V, I_{D} = -5A$	
Gate-Drain Charge	$Q_{gd}$	_	3.6	_	1		
Turn-On Delay Time	t <sub>D(ON)</sub>	_	3.7	_			
Turn-On Rise Time	t <sub>R</sub>	_	6.3	_	ns	$V_{GS} = -10V$ , $V_{DS} = -30V$ , $R_{GEN} = 6\Omega$ ,	
Turn-Off Delay Time	t <sub>D(OFF)</sub>	_	58.7	_	lio	$I_D = -5A$	
Turn-Off Fall Time	t <sub>F</sub>	_	26.1	_	<u> </u>		
Body Diode Reverse Recovery Time	t <sub>RR</sub>	_	14.85	_	ns	I <sub>S</sub> = -5A, dI/dt = 100A/μs	
Body Diode Reverse Recovery Charge	$Q_{RR}$	_	8.8		nC	$I_S = -5A$ , $dI/dt = 100A/\mu s$	

6. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

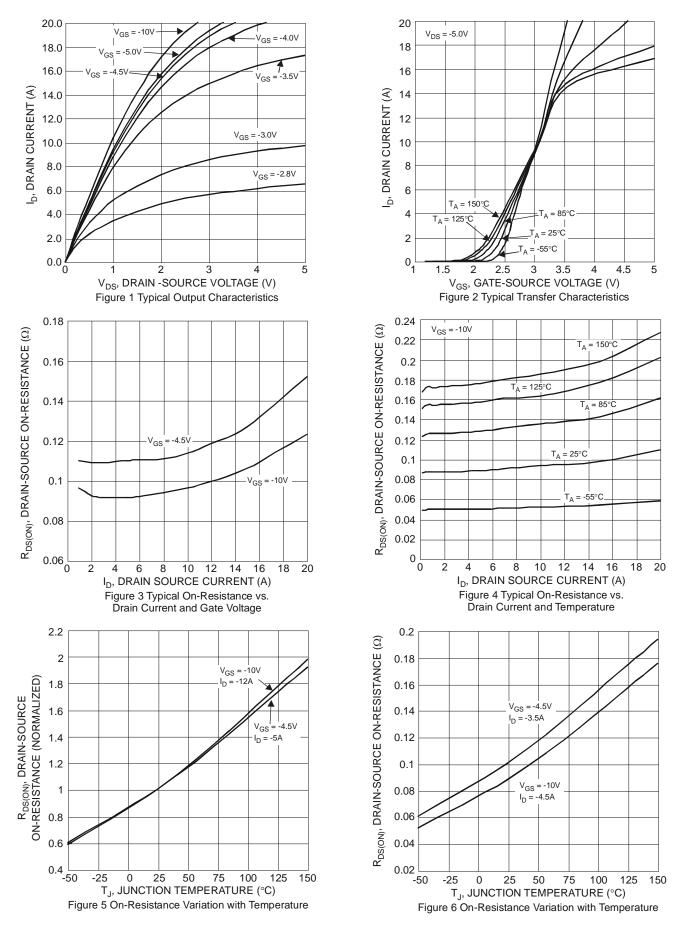
7. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.

8. UIS in production with L = 0.1mH, starting T<sub>A</sub> = +25°C.

9. Short duration pulse test used to minimize self-heating effect. Notes:

<sup>10.</sup> Guaranteed by design. Not subject to product testing.







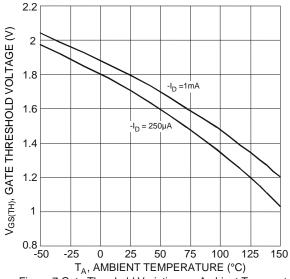
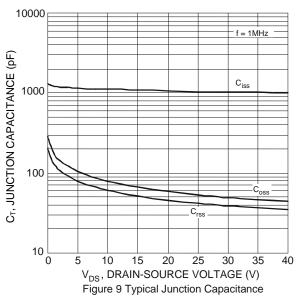
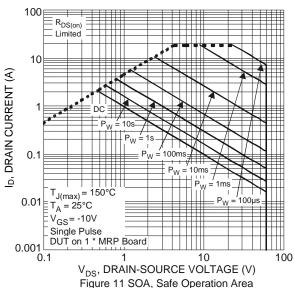
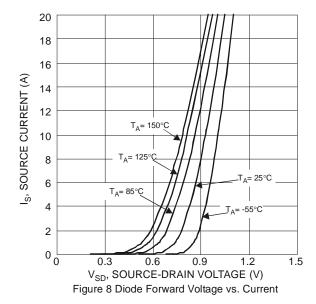
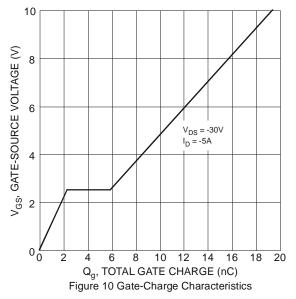


Figure 7 Gate Threshold Variation vs. Ambient Temperature

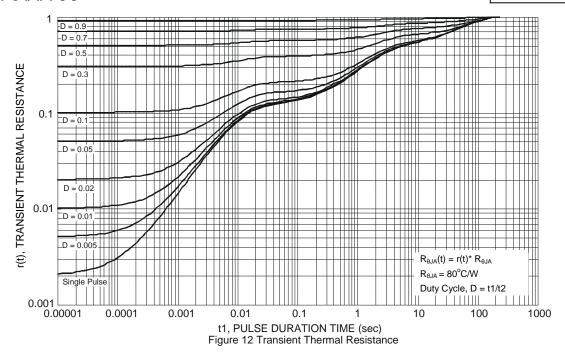






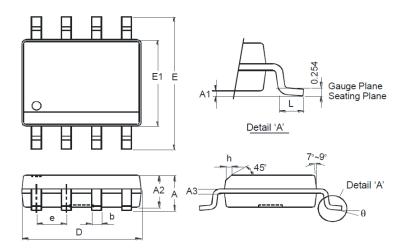






# **Package Outline Dimensions**

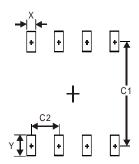
Please see http://www.diodes.com/package-outlines.html for the latest version.



SO-8				
Dim	Min	Max		
Α	-	1.75		
A1	0.10	0.20		
A2	1.30	1.50		
A3	0.15	0.25		
b	0.3	0.5		
D	4.85	4.95		
Е	5.90	6.10		
E1	3.85	3.95		
е	1.27 Typ			
h	-	0.35		
L	0.62	0.82		
θ	0°	8°		
All Dimensions in mm				

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions	Value (in mm)		
Х	0.60		
Y	1.55		
C1	5.4		
C2	1.27		



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